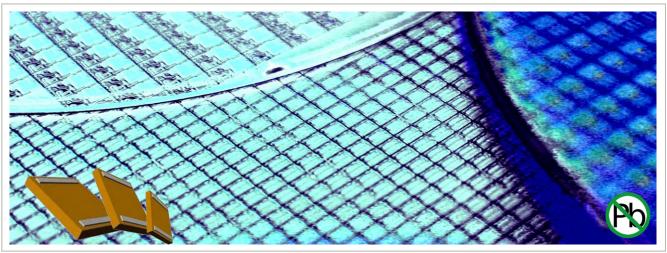


HSSC424.xxx - 0402 High Stability Silicon Capacitor

Rev 3.2



Key features

- Ultra high stability :
 - ◆ Temperature <±0.5% (-55 °C to +150 °C)
 - Voltage <0.1 %/V
 - ◆ Negligible aging <0.001% /1000hours
- Unique high capacitance in EIA/0402 package size, up to 100 nF
- High reliability (FIT <0.017 parts / billion hours)</p>
- Low leakage current down to 100 pA
- Low ESL and Low ESR
- Suitable with lead free reflow-soldering *Please refer to our assembly Application Note for further recommendations

Thanks to the unique IPDiA Silicon capacitor technology, most of the problems encountered in demanding application can be solved.

High Stability Silicon Capacitors are dedicated to applications where **Reliability** is the main parameter thanks to our end of production Burnin.

HSSC avoid the need to oversize the capacitor value for sensitive capacitive circuitry and offers a higher DC voltage stability.

This technology provides industry leading performances relative to the capacitor stability over the full operating voltage & temperature range.

The very high and stable insulation resistance of silicon capacitors can enhance up to 30 % the **battery lifetime** in mobile applications.

Key applications

- All demanding applications, such as medical, aerospace, automotive industry
- High stability applications
- Decoupling / Filtering / Charge pump (i.e.: Pacemakers / defibrillators)
- Devices with battery operations
- Replacement of X7R and NP0
- Downsizing

The IPDiA technology features a capacitor integration capability (up to 250nF/mm²) which allows a **smaller case size** than existing solutions to answer high volume constraints. This technology also offers **high reliability**, up to 10 times better than alternative capacitor technologies, such as Tantalum or MLCC, and eliminates cracking phenomena.

This Silicon based technology is RoHS compliant and compatible with lead free reflow soldering process.





Electrical specification

		Capacitance value								
		10	15	22	33	47	68			
		Contact	Contact	Contact	Contact	Contact	Contact			
	1 pF	IPDIA Sales	IPDIA Sales	IPDIA Sales	IPDIA Sales	IPDIA Sales	IPDIA Sales			
		100 pF:	150 pF:	220 pF:	330 pF:	470 pF:	680 pF:			
	10 pF	935.131.424.310	935.131.424.315	935.131.424.322	935.131.424.333	935.131.424.347	935.131.424.368			
+-1		1 nF:	1.5 nF:	2.2 nF:	3.3 nF:	4.7 nF:	6.8 nF:			
Init	0.1 nF	935.131.424.410	935.131.424.415	935.131.424.422	935.131.424.433	935.131.424.447	935.131.424.468			
)						47 nF:				
		10 nF:	15 nF:	22 nF:	33 nF:	935.131.424.547	Contact			
	1 nF	935.131.424.510	935.131.424.515	935.131.424.522	935.131.424.533	935.131.724.547	IPDIA Sales			
		100 nF:								
	10 nF	935.131.424.610								

(*\	Thinner thickness	(as low as 100	rum thick) available	see I ow Profile	Silicon C:	anacitor	product: LPS	c.

^(**) Extended temperature range (up to +250 °C) available, see Xtreme Temperature Silicon Capacitor product: XTSC

<u>Parameters</u>	<u>Value</u>		
Capacitance range	100 pF to 100 nF ^(***)		
Capacitance tolerances	±15 % ^(***)		
Operating temperature range	-55 °C to 150 °C (**)		
Storage temperatures	- 70 °C to 165 °C		
Temperature coefficient	<±0.5 %, from -55 °C to +150 °C		
Breakdown voltage (BV)	11, 30 V ^{***)}		
Capacitance variation versus RVDC	0.1 % /V (from 0 V to RVDC)		
Equivalent Serial Inductor (ESL)	Max 100 pH		
Equivalent Serial Resistor (ESR)	Max 400mΩ ^(***)		
Insulation resistance	100GΩ min @ 3V,from -55°C to +150°C		
Ageing	Negligible, < 0.001 % / 1000h		
Reliability	FIT<0.017 parts / billion hours,		
Capacitor height	Max 400 μm ^(*)		

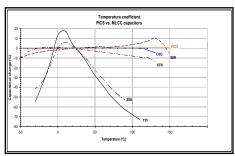


Fig.1 Capacitance change versus temperature variation compared with alternative dielectrics

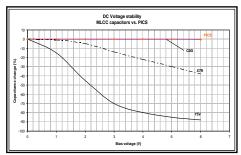


Fig.2 Capacitance change versus voltage variation compared with alternative dielectrics

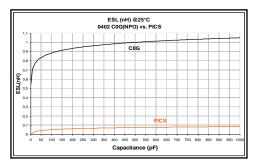
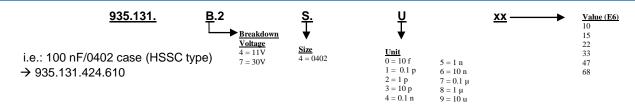


Fig.3 ESL versus capacitance value compared with alternative dielectrics

Part Number



Termination and Outline

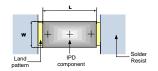
Termination

Lead-free nickel/solder coating compatible with automatic soldering technologies: reflow and manual.

Typical dimensions, all dimensions in mm.

Package outline

Тур.		0402		
Comp.	L	1.16±0.05		
size	W	0.66±0.05		



(0402 PCB footprint)

Packaging

Tape and reel, tray, waffle pack or wafer delivery.

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^(***) Other values on request.

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935152492510	935156424610	939113424610	935155424610	935151723510				